

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 23 February 2026, 11:17 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.09%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.464%
			GOLD, ELEMENTAL	7440-57-5	0.611%
			Tin elemental	7440-31-5	3.672%
			Elemental silicon	7440-21-3	95.253%
Encapsulation	EP (Epoxy resin)	74.05%	Carbon black	1333-86-4	1%
			Zinc borate hydrate	12513-27-8	5%
			Phenol, polymer with 1,4-bis(methoxymethyl)benzene	26834-02-6	10%
			4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	10%
			Magnesium hydroxide (Mg(OH) ₂)	1309-42-8	14%
			Silicon dioxide	60676-86-0	60%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.1%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.74%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	24.02%	SILVER, ELEMENTAL	7440-22-4	4.5%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	40.34%
			Elemental iron	7439-89-6	55.16%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-323_(EB)_Pb&H-free	Diode SMD	0.0046	g
